

产品规格承认书

SPECIFICATIONS

客户:

CUSTOMER: _____

产品名称:

DESCRIPTION: 地磁天线

客户型号:

CUSTOMER PART NO: _____

产品型号:

OUR MODEL NO: **PBX1608MA02**

日期:

DATE: _____

确认签字, 盖章后请返回承认书一份

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL"

WITH YOUR APPROVED SIGNATURES

核准		审核	刘飞	制作	刘小美
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客户承认签印	
日期	

UNLESS OTHER SPECIFIED TOLERANCES ON: X=± X.X=± X.XX=± ANGLES = ± HOLEDIA = ±		 PENG BAN XING 深圳市朋伴兴业科技有限公司
SCALE: N/A		UNIT: mm
DRAWN BY: Sera		CHECKED BY: XD
DESIGNED BY: Sera		APPROVED BY: XD
TITLE: CHIP2450-1608 Specification		DOCUMENT NO. 1608
		SPEC REV. P1

PBX1608MA02 Specification

Operating Temp. : -40°C~+85°C

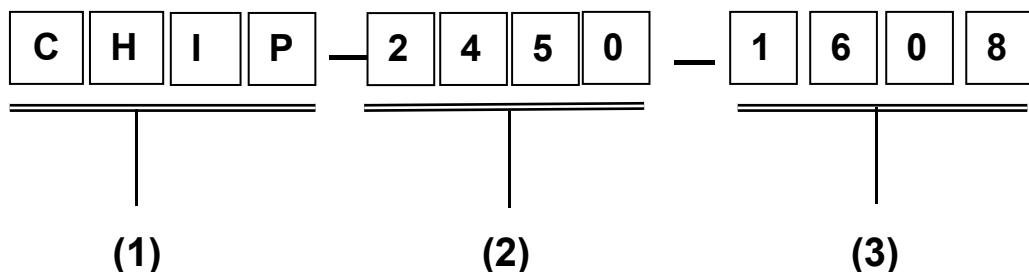
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

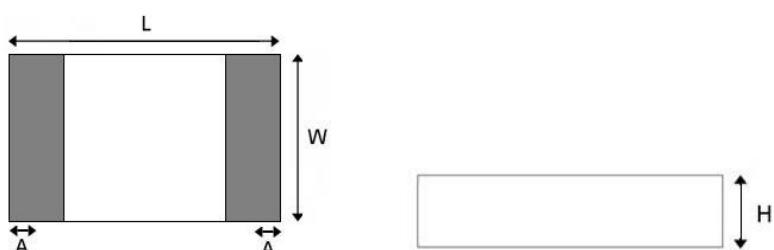
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 1.6*0.8

4. SHAPE AND DIMENSIONS:



L	W	H	A
1.6±0.2	0.8±0.2	0.8±0.2	0.3±0.1

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ANGLES = \pm **HOLE DIA** = \pm

SCALE: N/A

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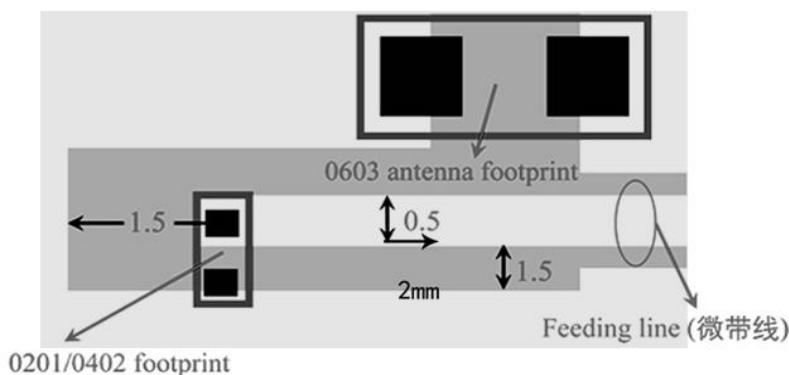
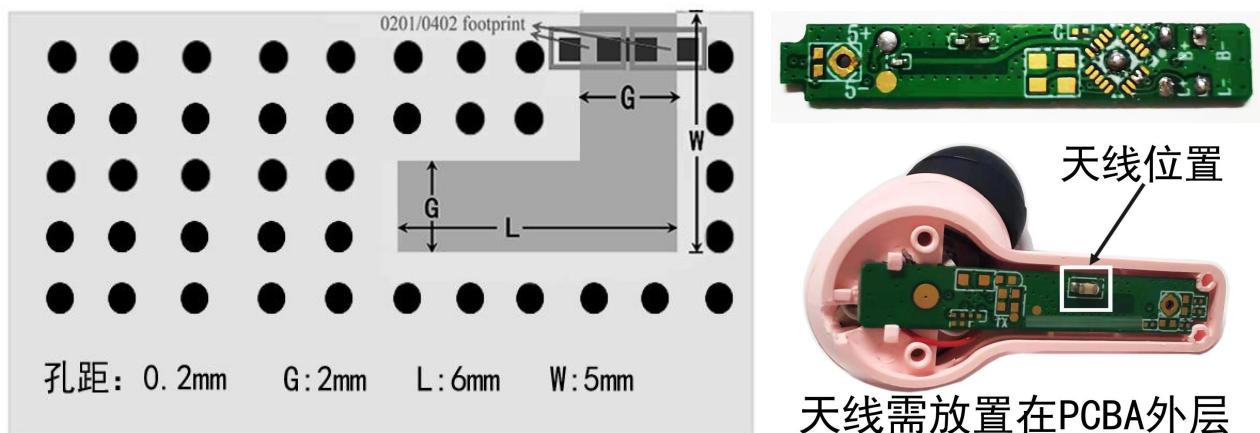
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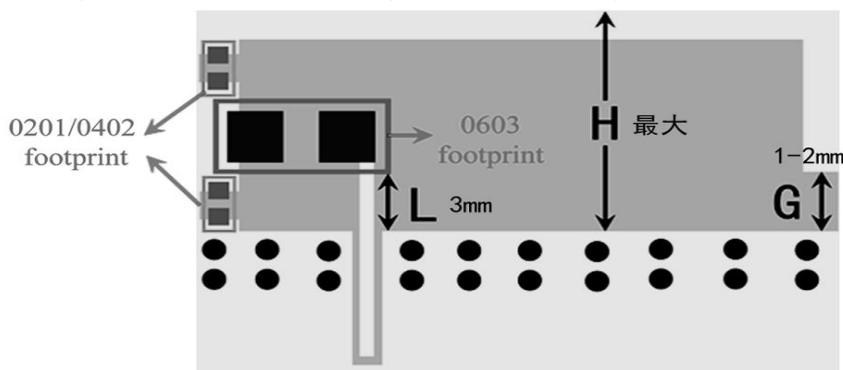
P1

- 天线位于 PCB 板内部或中间位置时（长条式耳机）：（单位：mm）



天线最优放置于中间区域，净空区周围最优需要至少一排过孔。

- 天线位于 PCB 板边缘位置时（入耳式耳机和部分长条式耳机）：



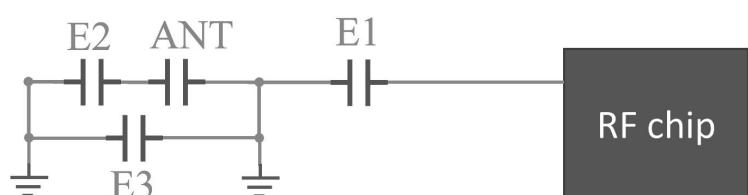
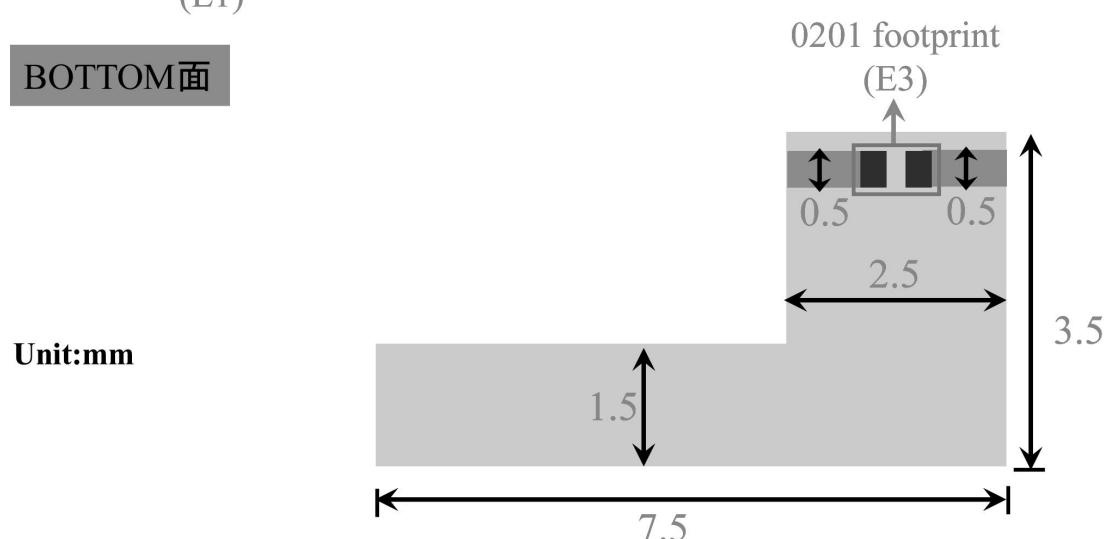
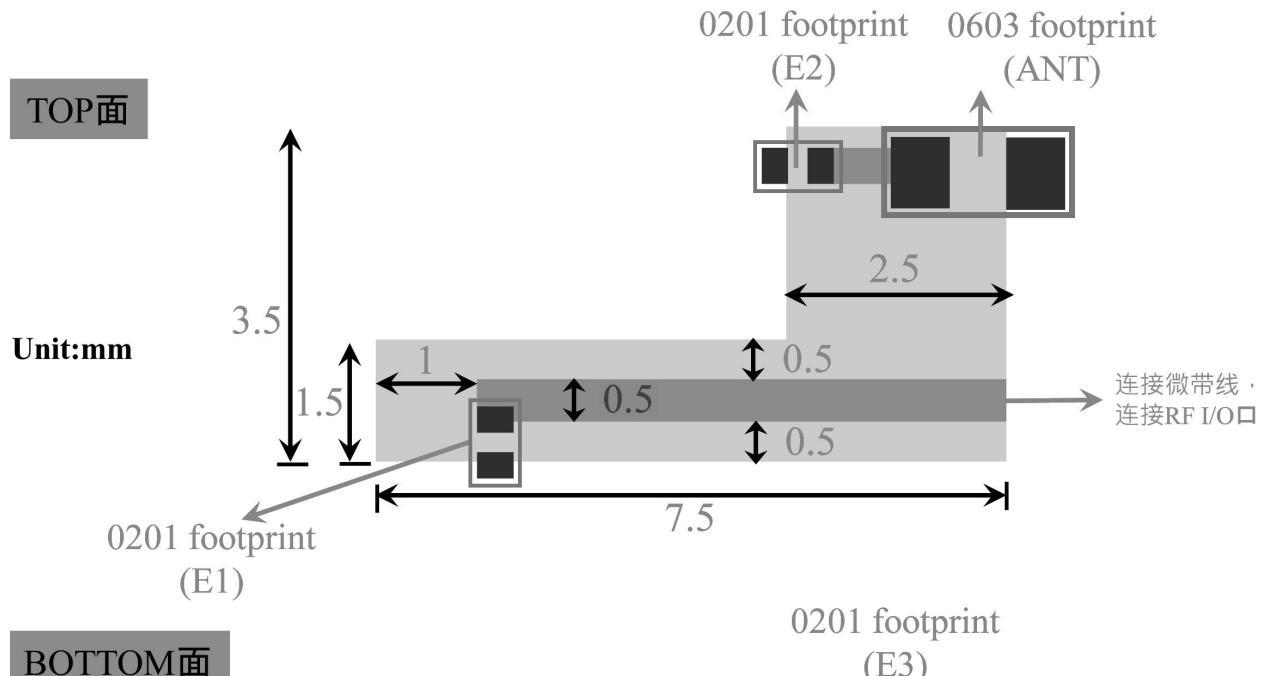
天线最优放置于 PCBA 的边缘；天线及其走线设置在单层。

设计标准：

1. 图中的尺寸仅作为参考；实际尺寸会根据不同版型进行优化。
2. 净空区周围最优需要至少一排过孔，孔径 0.3mm，与 PCBA 上的其它回路或物料进行隔离。

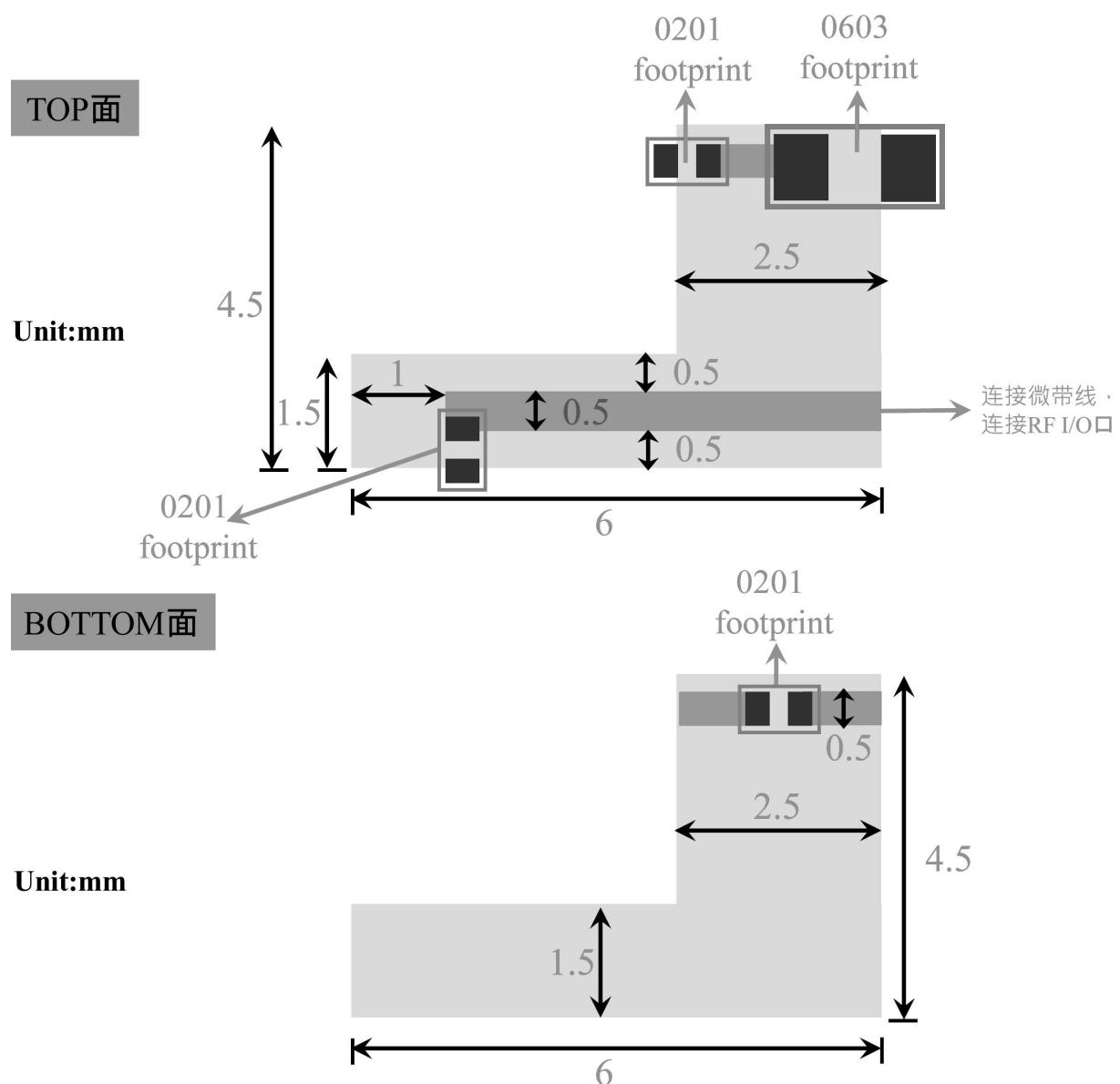
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天线封装方案一 (3.5mm×7.5mm)



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天线封装方案二 (4.5mm×6mm)



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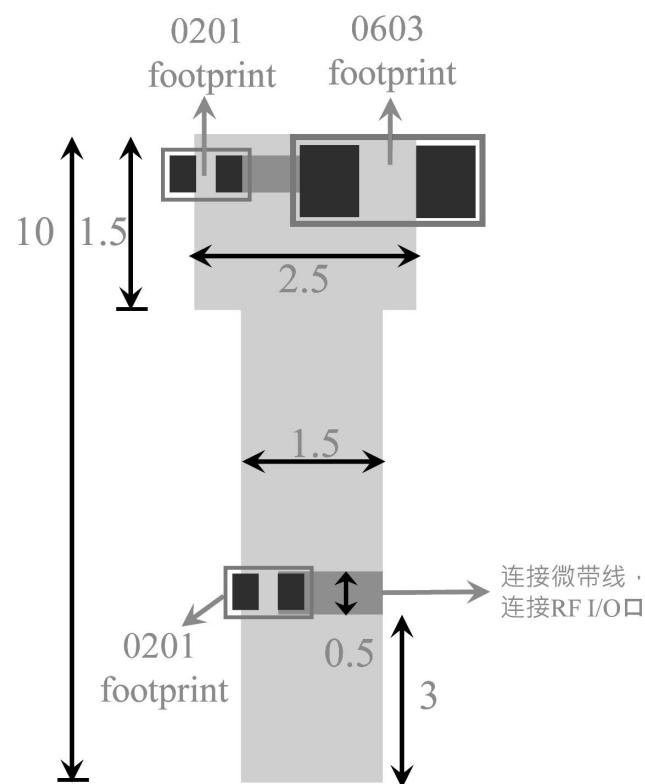
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P1

天线封装方案三 (1.5mm×10mm)

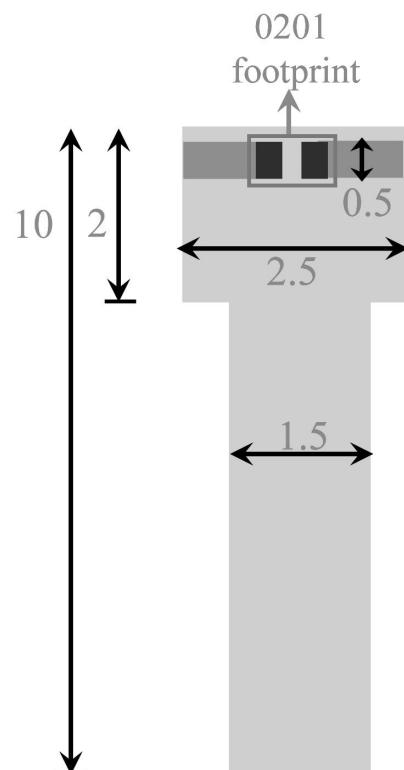
TOP面

Unit:mm



BOTTOM面

Unit:mm



UNLESS OTHER SPECIFIED TOLERANCES ON:
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SCALE: N/A

DRAWN BY: Sera

DESIGNED BY: Sera

UNIT: mm

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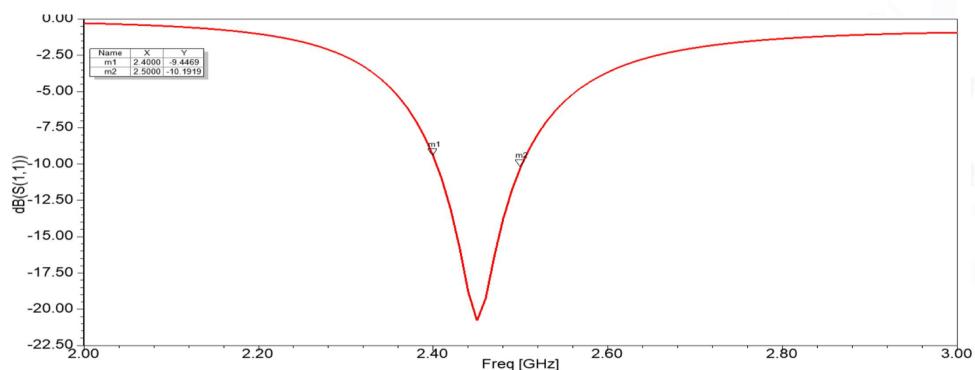
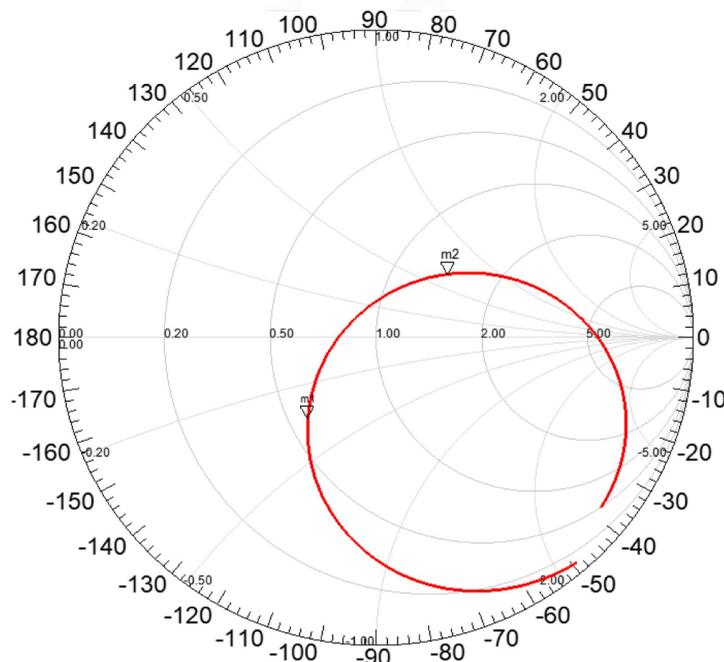
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P1

Electrical Characteristics

	Feature	Specification
1	Central frequency	2.45GHz
2	Bandwidth	>150MHz
3	Peak gain	2.78 dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves



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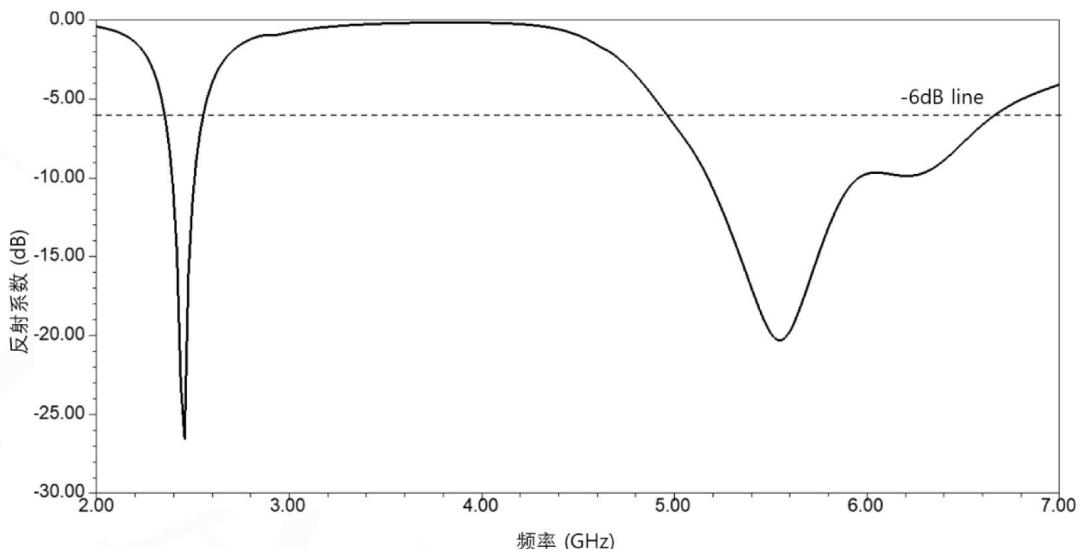
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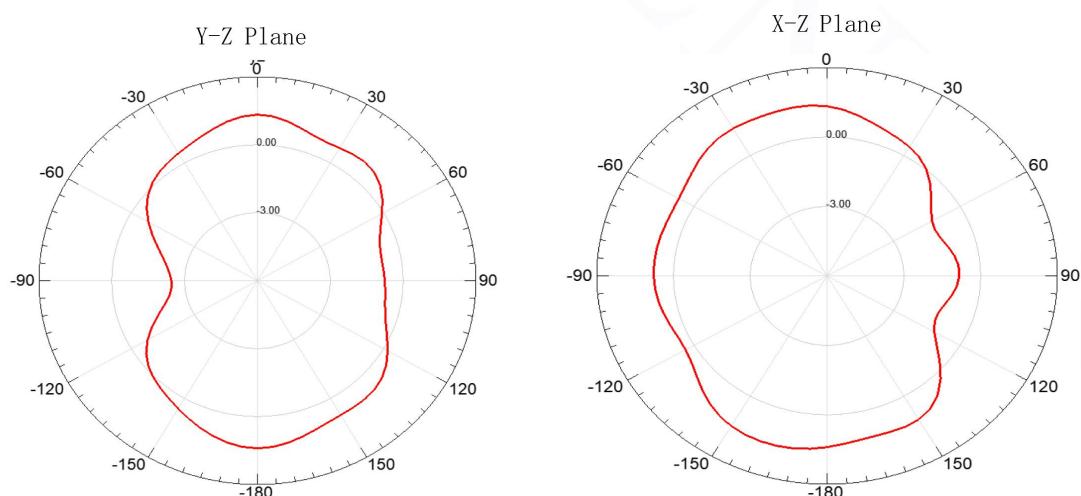
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Radiation Pattern

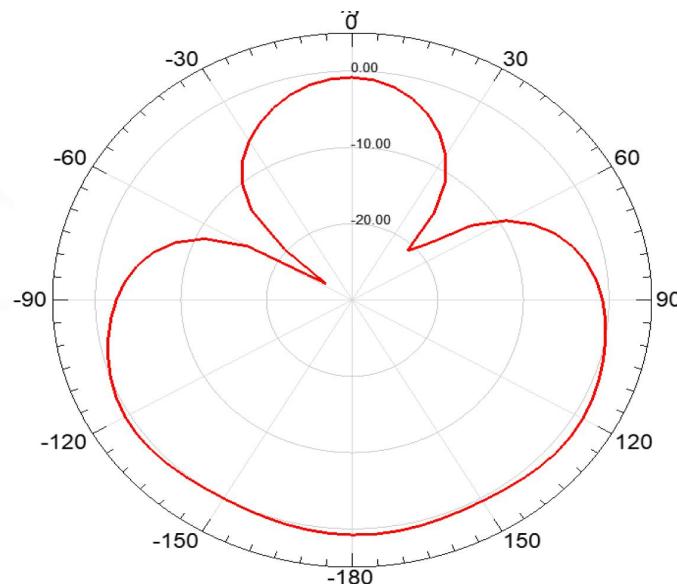


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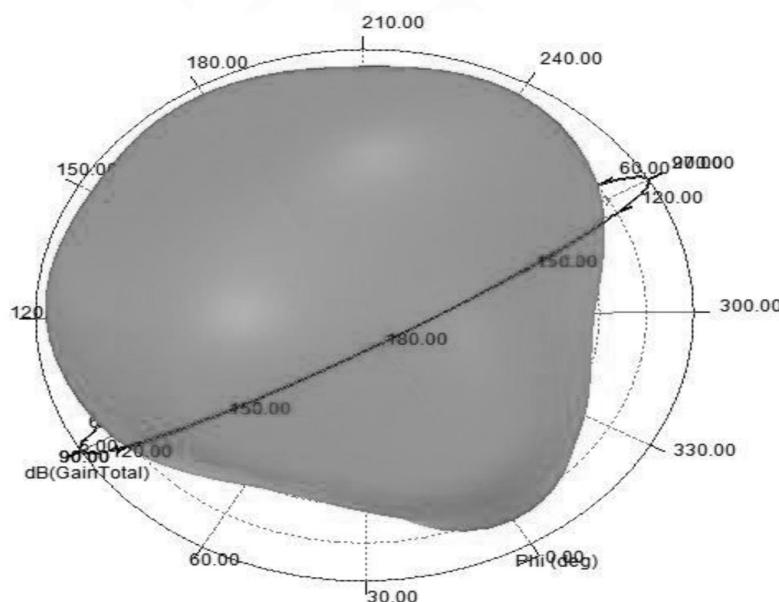


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3D Radiation Pattern



Frequency	2400MHz	2450MHz	2500MHz
Avg. gain	-1.92	-1.35	-1.56
Peak gain	1.79	2.78	2.66
Efficiency	74.55	80.25	76.98

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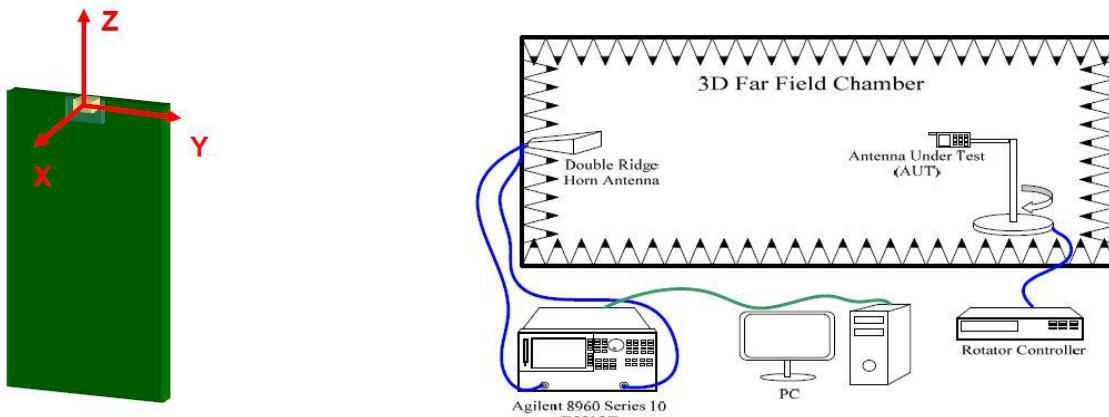
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Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at $-40^\circ C \pm 5^\circ C$, 2. Convert to $+105^\circ C$ (5 minutes) 3. 30 ± 3 minutes at $+105^\circ C \pm 5^\circ C$, 4. Convert to $-40^\circ C$ (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R. H. 2. Temperature: $85 \pm 5^\circ C$ 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: $150^\circ C \pm 5^\circ C$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: $-40^\circ C \pm 5^\circ C$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260 \pm 5^\circ C$ 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245 \pm 5^\circ C$ for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^\circ C$ and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

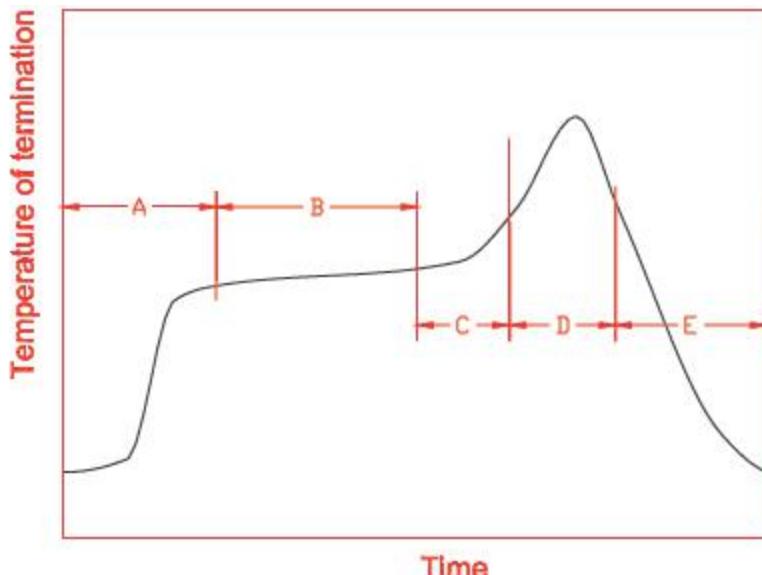
The temperature should be within $-40 \sim 85^\circ C$ and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : $-40^\circ C$ to $+105^\circ C$.

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8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

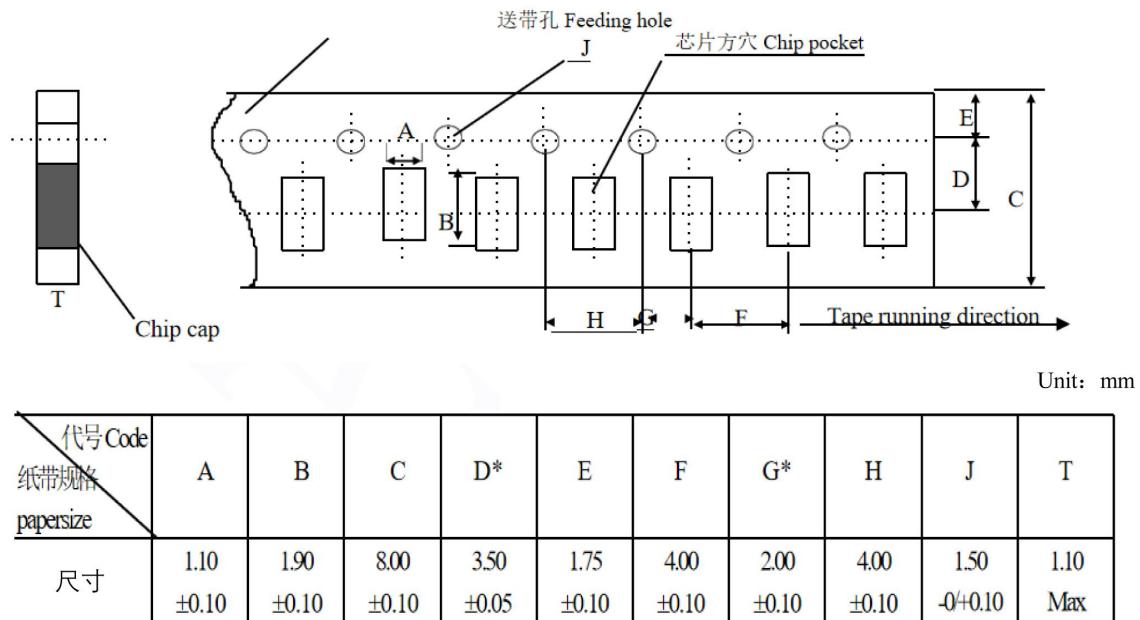
- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

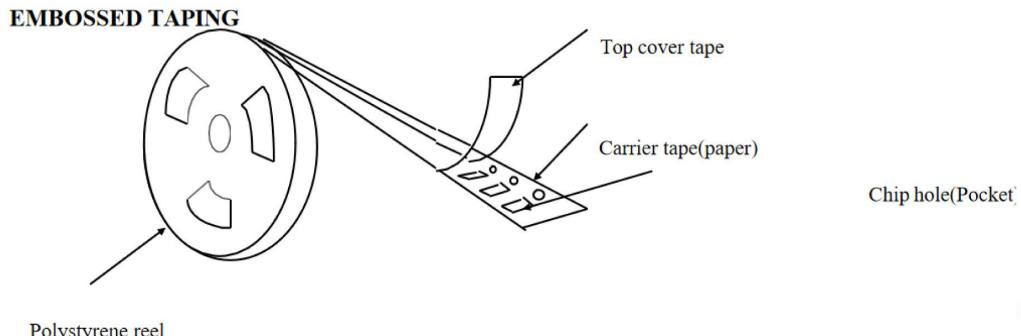
Note that excess of soldering volume will easily get crack the body of this product.

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Dimensions of paper taping:



Reel (4000 pcs/Reel)



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition).
Temperature:5~40°C /Relative Humidity:20~70%

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